

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE  
WASHINGTON, D.C. 20231**

Inventor: **Richard J. Pommer**  
Serial No: **Div. of 10/238,800**  
Filed: **September 9, 2002**  
For: **Alignment Plate with  
Matched Thermal Coefficient  
of Expansion**

Examiner: **Eric B. Compton**  
Art Unit: **3726**

**PRELIMINARY AMENDMENT**

Mail Stop Patent Application  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

Please enter the following preliminary amendment:

**IN THE CLAIMS**

Please cancel all allowed claims and add the following claims addressing subject matter in application serial number 10/238,800:

13. (Added) A multilayer interconnect, comprising:  
  
a plurality of dielectric layers, wherein at least two of the dielectric layers have different thermal coefficients of expansion and wherein the layers including a plurality of registration holes; and  
  
an alignment plate having tooling pins with a diameter larger than the diameters of the registration holes and having approximately a TCE that differs from the average TCE of the dielectric layers by less than 2 ppm/°C, wherein the plurality of layers onto the alignment plate.
14. (Added) The interconnect of claim 13, wherein the dielectric layers comprise polyimide.